L Number	Hits	Search Text	DB	Time stamp
1	145	(420/425).CCLS.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 11:06
14	89	high adj purity adj niobium	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 11:09
15	7745	sputtering adj target	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 11:09
2	126	high adj purity adj tantalum	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 11:09
16	5	(high adj purity adj niobium) and grain adj size	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 11:09
3	24	high adj purity adj tantalum	USOCR	2003/04/22 11:09
4	25	(high adj purity adj tantalum) and grain adj size	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 11:09
5	10	(high adj purity adj tantalum) and recrystalliz$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 11:09
6	137	(148/668).CCLS.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 11:09
7	101	(148/dig.158).CCLS.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 11:10
8	106	(148/dig.14).CCLS.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 11:10
9	192	(420/427).CCLS.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 11:10
10	111	148/422	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 11:10
11	2	"6348139"	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 11:10
19	11	sputtering adj target and (high adj purity adj tantalum)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 11:10
20	6	sputtering adj target and ((high adj purity adj tantalum) and grain adj size)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 11:10

12	77	tantalum adj2 metal and (texture or crystal adj2 orientation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 11:10
13	3	"01290766"	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 11:10
21	668	((148/422) or (148/668) or (148/dig.158) or (148/dig.14) or (420/425) or (420/427)).CCLS.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 11:10
17	23	extrud$4 near2 niobium	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 11:10
18	29	extrud$4 near2 tantalum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 11:10